

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t3009esc8-2.5#trmpbf

(Engineering Calculation)

SC70

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TOTAL MASS (g) : 0.01042

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.000464 | 1000000 | 44529.2421875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.003442 | 975000 | 330322.5 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000085 | 24000 | 8157.29589844 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000001 | 300 | 95.9681930542 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000002 | 700 | 191.936386108 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.003530 | 1000000 | 338767.71875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.003408 | 1000000 | 327071.09375 | | |
| | | External Plating Total: | | | | 0.003408 | 1000000 | 327071.09375 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000023 | 1000000 | 2207.26855469 | | |
| Internal Plating Total: | | | | 0.000023 | 1000000 | 2207.26855469 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000289 | 750000 | 27734.8066406 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000096 | 250000 | 9212.94628906 | | |
| Die Attach Total: | | | | 0.000385 | 1000000 | 36947.7539062 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.000147 | 58000 | 14107.3242188 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.002261 | 890000 | 216984.078125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000127 | 50000 | 12187.9609375 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000005 | 2000 | 479.840942383 | | |
| | | Encapsulation Total: | | | | 0.002540 | 1000000 | 243759.203125 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000070 | 1000000 | 6717.7734375 | | |
| | | | | | TOTAL MASS (g) : | 0.01042 | | |